

Smaller and sophisticated devices - yesterday's science fiction is today's reality. It's electronic technology making this possible. However, at the heart of every modern electronics is embedded - Printed Circuit Boards (PCBs).

At Tessolve, we are redefining the way these PCBs power the world. We transform technology with fabrication of time critical and advanced multi-layered PCBs.

# PILLARS OF PCB FABRICATION

- O Capable team of design engineers.
- Occupant over multi-layer design.
- A robust fabrication infrastructure.

### Wide Range of PCB Manufacturing.



Prototype models



High mix/low-mid volume varieties of finishing



| Single sided boards to multilayer stacks

#### Realizing Flexible Deliveries.



Quick-turn Sample to production order



Assembling of Prototypes

### SUPPORTING THE PCB JOURNEY: SPECTRUM, A WHOLLY OWNED SUBSIDIARY OF TESSOLVE

Tessolve acquired Spectrum Integrated Technologies Sdn. Bhd. on August 29, 2017. Tessolve now boasts a Printed Circuit Board (PCB) Fabrication unit in Johor Bahru in Malaysia.



Increased proficiency in Embedded System development



Cost reductions due to faster deliveries to customers



Advanced solutions in Chip Design, Testing and PCB Engineering

BENEFITS OF TESSOLVE'S FAB
TO CUSTOMER



Supporting semiconductor customers better especially those in Asia



Leading in end to end Semiconductor Engineering solutions

## A ROBUST PCB PORTFOLIO

#### **OVERVIEW**

Factory Space: 54,000 sq.ft.
 Capacity: 100,000 sq.ft.
 ISO 9001: 2015 Certified

#### **MATERIALS**

- Standard Tg FR4 (Tg = 130~140degC)
- High Temp Lead-Free FR4 (Tg = 170~230degC)
- Halogen-Free

#### **ENGINEERING SERVICES**

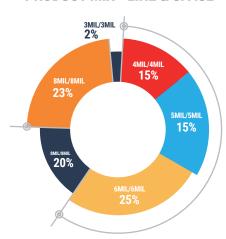
- QTA (3-10 days)
- Failure/Risk Analysis
- DFM

#### KEY TECHNICAL CAPABILITIES

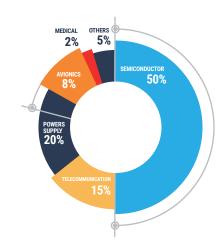
- 2~30 Layers
- Thick: 0.02~0.200" (0.5~5mm)
- I/L & O/L Lines/Spaces 3.0/3.0mil
- Panel Size (24"x27")
- Controlled Impedance (8%)
- RoHS, REACH, WEEE
- POFV & Buried Via
- Aspect Ratio 16:1
- Hybrid Stack-ups
- Wide range of Surface Finishing

### EXTENSIVE FABRICATION CAPABILITIES

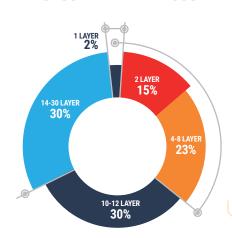
#### **PRODUCT MIX - LINE & SPACE**



#### **PRODUCT MIX - APPLICATIONS**



#### **PRODUCT MIX - LAYER COUNT**

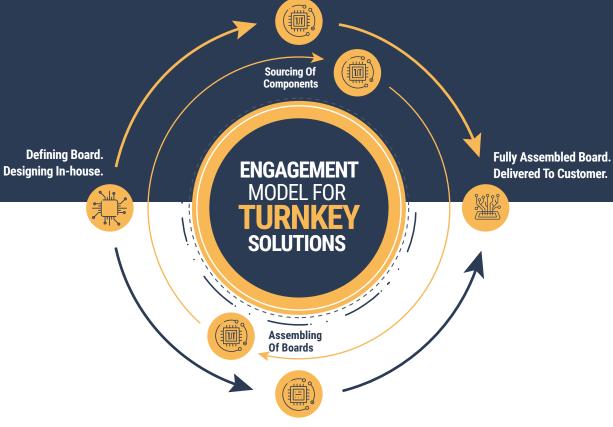




### WHY TESSOLVE FOR PCB FAB

Semiconductor engineering | End to end solutions | Prototypes to production

**Tessolve PCB Fabrication Unit** 



**Partner Fabrication Unit** 

